

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc3550edhc#trpbf

(Engineering Calculation)

DFN 5mm X 3mm Exp. Pad

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TOTAL MASS (g) : 0.038131

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001039 | 1000000 | 27248.171875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.017069 | 974800.0625 | 447641.0625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000411 | 23500 | 10778.6318359 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000015 | 850 | 393.380737305 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000015 | 850 | 393.380737305 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.017510 | 1000000 | 459206.46875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000817 | 1000000 | 21426.1914062 | | |
| | | External Plating Total: | | | | 0.000817 | 1000000 | 21426.1914062 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000391 | 1000000 | 10254.1240234 | | |
| Internal Plating Total: | | | | 0.000391 | 1000000 | 10254.1240234 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000583 | 750000 | 15289.3974609 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000194 | 250000 | 5087.72412109 | | |
| Die Attach Total: | | | | 0.000777 | 1000000 | 20377.1210938 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002274 | 130000 | 59636.5234375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.015041 | 860000 | 394455.96875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000175 | 10000 | 4589.44189453 | | |
| | | Encapsulation Total: | | | | 0.017490 | 1000000 | 458681.90625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000107 | 1000000 | 2806.1159668 | | |
| | | | | | TOTAL MASS (g) : | 0.038131 | | |